

at least a second electrode or an insulation layer formed on the second major surface opposite to said first major surface; and

at least a conductive member for connecting said first electrode with said second electrode or said insulation layer, said conductive member being formed along the outer circumference of at least a side of said semiconductor chip;

wherein said semiconductor device units are stacked on each other, and said conductive members are connected to each other,

wherein each of said conductive members is comprised of a conductive clip holding said first electrode together with said second electrode or said insulation layer, said conductive clip having elasticity for clamping objects.

9. A semiconductor device comprising:

a plurality of semiconductor device units, each of said semiconductor device units including:

a semiconductor chip;

at least a first electrode formed on the first major surface of said semiconductor chip,

at least a second electrode or an insulation layer formed on the second major surface opposite to said first major surface; and

at least a conductive member for connecting said first electrode with said second electrode or said insulation layer, said conductive member being formed along the outer circumference of at least a side of said semiconductor chip;

wherein said semiconductor device units are stacked on each other, and said conductive members are connected to each other,